Applications

- For Band 13 LTE applications
- LTE B13 handset, data cards, mobile routers



9 Pin 2.5x2.0 mm CSP Package

Product Features

- High Rejection in Band 14
- Usable bandwidth 10 MHz
- High Tx-Rx Isolation
- Low loss (or High attenuation)
- Superior Amplitude / Phase Balance
- Single-ended- Balanced Rx operation
- Ceramic chip-scale Hermetic Package (CSP)
- Small Size: 2.5 x 2.00 x 0.56 mm
- Hermetic RoHS compliant, Pb-free

General Description

The 856879 is a high-performance Temperature Compensated Surface Acoustic Wave (TC SAW) duplexer designed to meet the strict LTE requirements for use in Band 13.

856879 is specifically designed to meet the high performance expectations of insertion loss, isolation and BC14 rejection in LTE systems operating in B13 applications under all operating condition. The use of TC SAW technology guarantees these specifications up to the extended +90C operating condition.

The 856879 uses common packaging techniques to achieve the industry standard 2.5×2.0 mm footprint. The duplexer exhibits excellent power handling capabilities.

Temperature Compensated SAW; DC blocking capacitor required.

Functional Block Diagram



Pin Configuration

Pin # Balanced	Description
1, 8	Rx Output
3	Tx Input
6	Antenna/Phasing Inductor
2,4,5,7,9	Ground

Ordering Information

Part No.	Description	
856879	Packaged Part	
856879-EVB	Evaluation Board	
Standard T/R size = 10,000 units/reel.		

Absolute Maximum Ratings

Parameter	Rating
Operating Temperature	-30 to +90 °C
Storage Temperature	-30 to +90 °C
RF Input Power ⁽³⁾	+25 dBm

- 1. Operation of this device outside the parameter ranges given may cause permanent damage.
- 2. Specifications are not guaranteed over all operable conditions.
- 3. Input Power AT Tx Port with applied CW signal at 55 ℃ for 10,000 hours

Tx - Electrical Specifications ⁽¹⁾

Specified Temperature Range: ⁽²⁾ -30 to +90 °C

Parameter ⁽³⁾	Conditions	Min	Typical (4)	Max	Units
Center Frequency		-	782	-	MHz
Maximum Insertion Loss	777 – 787 MHz	-	2.2	2.5	dB
Amplitude/Passband Variation ⁽⁵⁾	777 – 787 MHz	-	0.75	1.2	dB p-p
Rejection/Attenuation ⁽⁶⁾	10 - 716 MHz 716 - 728 MHz 728 - 746 MHz 746 - 756 MHz 758 - 767 MHz 767 - 768 MHz 769 - 769 MHz 769 - 770 MHz 770 - 771 MHz 771 - 772 MHz 869 - 894 MHz 1554 - 1565 MHz 1565 - 1585 MHz 1565 - 1585 MHz 1597 - 1607 MHz 1805 - 1880 MHz 1930 - 1990 MHz 2110 - 2170 MHz 2331 - 2361 MHz 2400 - 2484 MHz 3108 - 3148 MHz	32 36 35 47 37 30 15 6 4 2 35 41 40 40 40 40 40 40 40 38 38 38 35	37 39 41 51 43 36 25 13 7 5 38 45 46 45 46 45 47 46 46 53 50 45	-	dB dB dB dB dB dB dB dB dB dB dB dB dB d
Return Loss at Tx	777 – 787 MHz	10	19	-	dB
Return Loss at Antenna	777 – 787 MHz	10	15	-	dB
Tx Impedance (single-ended) (7)		-	50	-	Ω
Antenna Impedance (single-ended) (7)		-	50	-	Ω
	Tx – Rx Specificatio	n			
Tx to Rx Isolation	777 – 787 MHz (Differential) 777 – 787 MHz (Common Mode Rejection) 746 – 749 MHz 749 – 752 MHz 752 – 756 MHz 1552 – 1574 MHz 2328 – 2361 MHz 3104 – 3148 MHz	55 60 50 53 60 60 50	62 65 55 57 58 74 70 60	- - - - - - -	dB dB dB dB dB dB dB dB

Notes:

1. All specifications are based on the TriQuint schematic for the main reference design shown on page 7

2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temp.

3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances

4. Typical values are based on average measurements at room temperature

5. Over a sliding 5 MHz window, in-band

6. Relative to zero dB

7. This is the optimum impedance in order to achieve the performance shown

Rx - Electrical Specifications ⁽¹⁾

Specified Temperature Range: ⁽²⁾ -30 to +90 °C

Parameter ⁽³⁾	Conditions	Min	Typical ⁽⁴⁾	Max	Units
Center Frequency		-	751	-	MHz
Maximum Insertion Loss	746 – 756 MHz	-	1.85	2.5	dB
Amplitude/Passband Variation ⁽⁵⁾	746 – 756 MHz	-	0.4	1.1	dB p-p
Rejection/Attenuation ⁽⁶⁾	650 – 729 MHz 729 – 736 MHz 777 – 787 MHz 793 – 805 MHz 805 – 3200 MHz 3200 – 4200 MHz 4200 – 6000 MHz	27 27 55 33 22 30 13	31 30 60 39 27 35 27	- - - - - - -	dB dB dB dB dB dB dB dB
Return Loss at Rx	746 – 756 MHz	10	15	-	dB
Return Loss at Antenna	746 – 756 MHz	10	17	-	dB
Output Phase Balance	746 – 756 MHz	-5	-	+5	degree
Output Amplitude Balance	746 – 756 MHz	-1.0	-	1.0	dB
IMR2 ^{(7) (a,b)}		-	-110	-106	dBm
IMR3 ^{(7) (c,d)}		-	-120	-109	dBm
Rx Impedance (balanced) (8)		-	100	-	Ω
Antenna Impedance (single-ended) (8)		-	50	-	Ω

Notes:

- 1. All specifications are based on the TriQuint schematic for the main reference design shown on page 7
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temp
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 4. Typical values are based on average measurements at room temperature
- 5. Over a sliding 5 MHz window, in-band
- 6. Relative to zero dB
- 7. All power levels are referenced to the antenna port. Two CW tones are applied at frequencies f1 and f2, and the resultant intermodulation product in the Rx band is measured. The first tone is applied to the Tx port, in the range f1 = 777 to 787 MHz, at +21.5 dBm (referenced to the antenna port). The second tone is -15 dBm, applied to the antenna port at f2, with the following four cases:
 - a. f2 = 31 MHz
 - b. f2 = 2 * f1 31 MHz
 - c. f2 = f1 + 31 MHz
 - d. f2 = 3 * f1 31 MHz
 - The intermodulation product is measured at f1 31 MHz.
- 8. This is the optimum impedance in order to achieve the performance shown

Reference Design – Ant - 50 SE In, Tx - 50 SE Out , Rx - 100 Bal Out

Schematic



Notes:

- 1. Actual matching values may vary due to PCB layout and parasitic
- 2. If the DC level on any RF port is greater than 3V, it is recommended to add external DC block as needed. If not, no additional external components are required
- 3. TC SAW: DC blocking capacitor required <remove if not applicable>

PC Board



Mounting Configuration



Notes:

- 1. 3-layer board top, middle & bottom layer: 1 oz copper
- 2. Substrates: .031" thick FR4 dielectric.
- Finish plating: Nickel: 3-8µm thick, Gold: .03-.2µm thick
- 4. Hole plating: Copper min .0008µm thick

Notes:

- 1. Top view of the duplexer.
- 2. All dimensions are in millimeters.
- 3. This footprint represents a recommendation only.
- 4. This drawing specifies the mounting pattern used on the TriQuint evaluation board for this product. Some modification may be necessary to suit end user assembly materials and processes.

Bill of Material				
Reference Des.	Value	Description	Manuf.	Part Number
L1_Ant	13 nH	Coil Wire-wound, 0603, y%	MuRata	LQW15AN13NH00
L2_Rx	30 nH	Coil Wire-wound, 0603, y%	MuRata	LQW15AN30NG00
SMA	N/A	SMA connector	Radiall USA	9602-1111-018
PCB	N/A	3-layer	Multiple	

Tx - Typical Performance on TriQuint EVB (at room temperature)











Rx - Typical Performance on TriQuint EVB (at room temperature)



Tx - Rx Isolation - Typical Performance on TriQuint EVB (at room temperature)





Package Information, Marking and Dimensions



Package Style: CSP-10KT Dimensions: 2.5 x 2.00 x 0.56 mm

Body: Al_2O_3 ceramic Lid: *Kovar or Alloy 42, Au over Ni* plated Terminations: *Au* plating 0.5 - 1.0µm, over a 2-6µm *Ni* plating

The date code consists of:

WW = 2 digit week,

Y = last digit of year,

M = manufacturing site code

Notes:

- 1. All dimensions shown are typical in millimeters
- 2. All tolerances are ± 0.15 mm except overall length and width ± 0.10 mm
- 3. An asterisk (*) in front of the marking code indicates prototype.

Tape and Reel information

Standard T/R size = 10,000 units/reel. All dimensions are in millimeters



Not For New Designs. Consider TQQ1013 as an Alternative **TriQuint** ⁸⁵⁶⁸⁷⁹ ^{782/751 MHz Duplexer}

Product Compliance Information

ESD Sensitivity Ratings



Caution! ESD-Sensitive Device

ESD Rating: Class 0 Value: Passes ≤ 150V min. Test: Electrostatic Discharge Sensitivity Testing, Human Body Model (HBM) - component level Standard: ESDA/JEDEC JS-001-2012

ESD Rating:Class AValue:Passes ≤ 150V min.Test:Machine Model (MM)Standard:JEDEC Standard JESD22-A115

MSL Rating

Not applicable. Hermetic package.

Solderability

Compatible with both lead-free (260 °C maximum reflow temperature) and tin/lead (245 °C maximum reflow temperature) soldering processes.

Refer to **Soldering Profile** for recommended guidelines.

RoHs Compliance

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄0₂) Free
- PFOS Free
- SVHC Free

Contact Information

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